



Material Content Data Sheet



Sales Product Name		TLE9461ES V33		Issued		2. August 2018			
MA#		MA002361638							
Package		PG-TSDSO-24-1		Weight*		109.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.843	1.68	1.68	16794	16794	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142		
		non noble metal	zinc	7440-66-6	0.062	0.06		567	
		non noble metal	iron	7439-89-6	1.244	1.13		11334	
wire	non noble metal	non noble metal	copper	7440-50-8	50.505	46.03	47.23	460199	472242
		non noble metal	copper	7440-50-8	0.354	0.32	0.32	3227	3227
		encapsulation	organic material	carbon black	1333-86-4	0.156	0.14		1425
encapsulation	plastics	epoxy resin	-	6.097	5.56		55559		
		inorganic material	silicondioxide	60676-86-0	45.860	41.79	47.49	417877	474861
leadfinish	non noble metal	tin	7440-31-5	2.759	2.51	2.51	25143	25143	
plating	noble metal	silver	7440-22-4	0.178	0.16	0.16	1622	1622	
glue	plastics	epoxy resin	-	0.168	0.15		1528		
		noble metal	silver	7440-22-4	0.503	0.46	0.61	4583	6111
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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